

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC9502xxxxDR-G
Typical Mass: 12 mg

| Part name | Weight(mg) | Material name | Ratio(ppm) | CAS number |
|--------------|------------|-----------------|------------|------------|
| Silicon chip | 1.194 | Silicon | 99500 | 7440-21-3 |
| | - | Arsenic | 6 | 7440-38-2 |
| Lead pad | 2.287 | Nickel | 190600 | 7440-02-0 |
| | 0.104 | Silver | 8700 | 7440-22-4 |
| | 0.023 | Gold | 1900 | 7440-57-5 |
| Die attach | 0.064 | Silver | 5300 | 7440-22-4 |
| | 0.017 | Epoxy Resin | 1400 | — |
| | 0.004 | Phenol Resin | 400 | — |
| Bonding wire | 0.118 | Gold | 9800 | 7440-57-5 |
| Resin | 7.166 | Silica | 597100 | 60676-86-0 |
| | 0.409 | Epoxy Resin | 34100 | — |
| | 0.369 | Phenol Resin | 30700 | — |
| | 0.245 | Metal Hydroxide | 20400 | — |

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."